

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Chi Wah CHENG et al

Date: January 8, 2002

Serial No.:

Group Art Unit:

Filed:

Examiner:

For: APPARATUS AND METHOD OF PLACING SOLDER BALLS ONTO A SUBSTRATE

U.S. Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

AMENDMENT/SUBMISSION

Prior to examination, please amend the application as follows.

FEE CALCULATION

Any additional fee required has been calculated as follows:

_____ If checked, "Small Entity" status is claimed.

	NO. CLAIMS AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR		EXTRA PRESENT		RATE	ADDIT. FEE
TOTAL	24	MINUS	20	* =	4	X	(\$9 SE or \$18)	\$ 72.00
INDEP.	2	MINUS	3	** =	0	X	(\$42 SE or \$84)	\$
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM						X	(\$140 SE or \$280)	\$
								TOTAL \$ 72.00

* not less than 20

** not less than 3

If any additional payment is required, a check which includes the calculated fee of \$72.00 (OFGS Check No. 8026) is attached.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee during the prosecution of this application is not paid, the Patent Office is authorized to charge the underpayment to Deposit Account No. 15-0700.